

FOR IMMEDIATE RELEASE

TRI Features 3D Micro SMD Inspection at SEMICON Taiwan 2017

[July 21, 2017 – Taipei, Taiwan] Test Research, Inc. (TRI) will feature new 3D SPI and 3D AOI solutions specialized at micro SMD inspection at SEMICON Taiwan. Combining 5.5 µm resolution with optional vacuum fixtures, TRI inspection systems are ready to inspect micro components on a variety of substrates. Visit us at booth **908** on 4F at Taipei Nangang Exhibition Center on **September 13 ~ 15, 2017** and discover TRI's latest solutions for the semiconductor and electronics industry.

Presented at SEMICON Taiwan, TRI's 2017 booth will feature the TR7007Q SPI and brand new TR7500QE 3D AOI systems based on TRI's latest digital fringe projection technology. The micro SMD specialized TR7700E SIII AOI inspection system includes a vacuum-based fixture for accurate handling of thin and flexible substrates.

**TR7500QE 3D AOI**

Discover TRI's new micro SMD and packaging inspection solutions at booth **908** on **4F** of **SEMICON Taiwan 2017**.

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About TRI

TRI offers the most robust product portfolio in the industry for Automatic Test and Inspection solutions. From Solder Paste Inspection (SPI), Automated Optical Inspection (AOI), and 3D Automated X-ray Inspection (AXI) systems to Manufacturing Defect Analyzers (MDAs) and In-Circuit Test equipment, TRI provides the most cost-effective solutions to meet a comprehensive range of manufacturing Test and Inspection requirements. Learn more at <http://www.tri.com.tw>. For sales and service information, write us at marketing@tri.com.tw or call +886-2-2832 8918.